

L Number	Hits	Search Text		Time stamp
7	2	6136128.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/10/07 11:36
13	0	6424033.URPN.	USPAT	2002/10/07 12:14
14	13	("5475040" "5583378" "5786631" "5834337" "5843810" "5891755" "5907189" "5910010" "5930893" "6011304" "6175157" "6215180" "6218202").PN.	USPAT	2002/10/07 12:14
15	560	(438/108).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/07 12:36
16	522	(438/124).CCLS.	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/07 12:36
-	1	"20020084532"	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/02 13:16
-	1345	(257/778).CCLS.	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/02 11:19
-	20	((257/778).CCLS.) and lid same substrate same seal\$8	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/02 17:30
-	8	("5077633" "5289337" "5291371" "5367196" "5442234" "5510649" "5883430" "5909057").PN.	USPAT	2002/10/02 11:25
-	574	(257/796).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/02 11:29
-	2	((257/796).CCLS.) and lid same substrate same seal\$8	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/02 11:30
-	392	lid same substrate same seal\$8 and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/02 15:22
-	25	("2014524" "2774747" "3401126" "3429040" "3788561" "4113981" "4395184" "4442966" "4519859" "4793883" "5046415" "5056296" "5074947" "5112554" "5196371" "5237130" "5383997" "5427642" "5539153" "5575956" "5611140" "5622585" "5667884" "5742007" "5932875").PN.	USPAT	2002/10/02 11:39
-	2	6136128.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/02 11:40

-	19	("2014524" "2774747" "3401126" "3429040" "4113981" "4395184" "4442966" "4793883" "5046415" "5056296" "5074947" "5196371" "5237130" "5383997" "5539153" "5611140" "5622585" "5667884" "5932875").PN.	USPAT	2002/10/02 11:40
-	22	("2014524" "2774747" "3401126" "3429040" "4113981" "4395184" "4442966" "4793883" "4833102" "5046415" "5056296" "5074947" "5196371" "5237130" "5383997" "5539153" "5575956" "5611140" "5622585" "5667884" "5932875" "5950074").PN.	USPAT	2002/10/02 11:51
-	26	("4159221" "4530152" "4890383" "5001829" "5043004" "5102829" "5105260" "5126818" "5192681" "5230759" "5241133" "5250470" "5278429" "5336931" "5414300" "5422615" "5436203" "5474957" "5578525" "5593926" "5641713" "5742007" "5776798" "5801074" "5950074" "6034429").PN.	USPAT	2002/10/02 11:55
-	42	controlled with collapsed with connection and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/10/02 13:17
-	4	("4231154" "4979015" "5288944" "5506448").PN.	USPAT	2002/10/02 14:36
-	163	lid same substrate same seal\$8 and (438/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/10/02 16:26
-	120	(lid same substrate same seal\$8 and (438/\$).ccls.) not (lid same substrate same seal\$8 and (257/\$).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/10/02 15:24
-	21	("4748495" "5276586" "5366688" "5372296" "5434745" "5465470" "5528462" "5545473" "5552635" "5585671" "5591034" "5604978" "5623394" "5789810" "5881944" "5881945" "5889323" "5982038" "6041501" "6091603" "6218730").PN.	USPAT	2002/10/02 15:27
-	516	(sink cover) same substrate same seal\$8 and (438/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/10/02 17:03
-	460	((sink cover) same substrate same seal\$8 and (438/\$).ccls.) not (lid same substrate same seal\$8 and (438/\$).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/10/02 17:03
-	460	((((sink cover) same substrate same seal\$8 and (438/\$).ccls.) not (lid same substrate same seal\$8 and (438/\$).ccls.) not (lid same substrate same seal\$8 and (257/\$).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/10/02 17:15
-	3636	(gap vent break)same lid same seal\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/10/02 17:33

-	1	6,457,474.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/10/03 11:42
-	1	"5874845".PN.	USPAT	2002/10/03 11:29
-	4	("4209797" "4920391" "5675160" "5771189").PN.	USPAT	2002/10/03 11:29
-	2770	adhesive with pattern with (lid cover plate sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/03 12:03
-	502	(adhesive with pattern with (lid cover plate sink)) and adhesive with pattern with (lid cover plate sink)same substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/03 11:47
-	52	((adhesive with pattern with (lid cover plate sink)) and adhesive with pattern with (lid cover plate sink)same substrate) and (257/\$.ccls. 438/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/03 11:53
-	160	(IC chip die) and ((adhesive with pattern with (lid cover plate sink)) and adhesive with pattern with (lid cover plate sink)same substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/03 11:54
-	115	((IC chip die) and ((adhesive with pattern with (lid cover plate sink)) and adhesive with pattern with (lid cover plate sink)same substrate)) not (((adhesive with pattern with (lid cover plate sink)) and adhesive with pattern with (lid cover plate sink)same substrate) and (257/\$.ccls. 438/\$.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/10/03 11:54
-	73	sealant with pattern with (lid cover plate sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/10/03 15:14
-	44	4949084.URPN.	USPAT	2002/10/07 12:36
-	1	"4420820".PN.	USPAT	2002/10/03 15:21
-	44	4949084.URPN.	USPAT	2002/10/03 15:22